

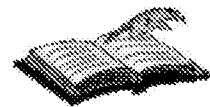
PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT4468107

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the DOC DATE(S) OF FOLLOWING INVENTORS: SHANG-CHIH HSIEH, TING-WEI CHIANG AND CHUN-FU CHEN previously recorded on Reel 042459 Frame 0920. Assignor(s) hereby confirms the DOC DATE(S) OF FOLLOWING INVENTORS: SHANG-CHIH HSIEH, TING-WEI CHIANG AND CHUN-FU CHEN SHOULD BE 09/26/2014..
RESUBMIT DOCUMENT ID:	504398199
CONVEYING PARTY DATA	
Name	Execution Date
SHANG-CHIH HSIEH	09/26/2014
HUI-ZHONG ZHUANG	09/26/2014
TING-WEI CHIANG	09/26/2014
CHUN-FU CHEN	09/26/2014
HSIANG-JEN TSENG	09/26/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15601697
CORRESPONDENCE DATA	
Fax Number:	(703)518-5499
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7036841111
Email:	tsmc@ipfirm.com
Correspondent Name:	HAUPTMAN HAM, LLP (TSMC)
Address Line 1:	2318 MILL ROAD
Address Line 2:	SUITE 1400
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	T5057-883UA

NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	06/20/2017
Total Attachments: 6 source=EfiledCorrectAssignment2017-06-16#page1.tif source=EfiledCorrectAssignment2017-06-16#page2.tif source=EfiledCorrectAssignment2017-06-16#page3.tif source=EfiledCorrectAssignment2017-06-16#page4.tif source=EfiledCorrectAssignment2017-06-16#page5.tif source=EfiledCorrectAssignment2017-06-16#page6.tif	

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>SHANG-CHIH HSIEH</td><td>09/26/2016 09/26/2014</td></tr><tr><td>HUI-ZHONG ZHUANG</td><td>09/26/2014</td></tr><tr><td>TING-WEI CHIANG</td><td>09/28/2016 09/26/2014</td></tr><tr><td>CHUN-FU CHEN</td><td>09/28/2016 09/26/2014</td></tr><tr><td>HSIANG-JEN TSENG</td><td>09/26/2014</td></tr></tbody></table>	Name	Execution Date	SHANG-CHIH HSIEH	09/26/2016 09/26/2014	HUI-ZHONG ZHUANG	09/26/2014	TING-WEI CHIANG	09/28/2016 09/26/2014	CHUN-FU CHEN	09/28/2016 09/26/2014	HSIANG-JEN TSENG	09/26/2014	
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<table><tr><td>Name:</td><td>TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.</td></tr><tr><td>Street Address:</td><td>NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK</td></tr><tr><td>City:</td><td>HSINCHU</td></tr><tr><td>State/Country:</td><td>TAIWAN</td></tr><tr><td>Postal Code:</td><td>300</td></tr></table>	Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	City:	HSINCHU	State/Country:	TAIWAN	Postal Code:	300			
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Application Number:	15601697												

PATENT**REEL: 042757 FRAME: 0099**

CORRESPONDENCE DATA**Fax Number:** (703)518-5499**Phone:** 7036841111**Email:** tsmc@ipfirm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Correspondent Name: HAUPTMAN HAM, LLP (TSMC)**Address Line 1:** 2318 MILL ROAD**Address Line 2:** SUITE 1400**Address Line 4:** ALEXANDRIA, VIRGINIA 22314**ATTORNEY DOCKET NUMBER:** T5057-883UA**NAME OF SUBMITTER:** RANDY A. NORANBROCK**Signature:** /Randy A. Noranbrock/**Date:** 05/22/2017**Total Attachments: 2**

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Docket No. T5057-883U
TSMC2013-0379

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|---------------------|---------------------|
| 1) Shang-Chih HSIEH | 4) Chun-Fu CHEN |
| 2) Hui-Zhong ZHUANG | 5) Hsiang-Jen TSENG |
| 3) Ting-Wei CH IANG | |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

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(a) for which an application for United States Letters Patent was filed on 2014-04-15, and identified by United States Patent Application No. 14/253,205; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Shang-Chih Hsieh
Name: Shang-Chih HSIEH

2014/4/26
Date:

2) Hui Zhong Zhuang
Name: Hui-Zhong ZHUANG

2014/9/26
Date:

3) Ting-Wei CHIANG
Name: Ting-Wei CHIANG

9/26/2014
Date:

4) Chun-Fu CHEN
Name: Chun-Fu CHEN

9/26/2014
Date:

5) Hsiang-Jen Tseng
Name: Hsiang-Jen TSENG

9/26 /2014
Date: